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Contents

vii **Authors** Conference Committee ix AI AND MACHINE LEARNING 11328 03 Machine Learning using retarget data to improve accuracy of fast lithographic hotspot **detection** [11328-2] 11328 05 Implementing Machine Learning OPC on product layouts [11328-4] Advanced memory cell design optimization with inverse lithography technology [11328-5] 11328 06 **ADVANCED DESIGNS** 11328 07 Standard cell architectures for N2 node: transition from FinFET to nanosheet and to forksheet **device** [11328-6] 11328 08 Approaches for full coverage physical design space exploration and analysis by synthetic layout generation [11328-7] 11328 09 An automated system for checking process friendliness and routability of standard cells [11328-8] 11328 0A Sequential 3D standard cell 4T architecture using design crenellation and self-aligned MOL for N2 technology and beyond [11328-9] **PATTERN MATCHING** 11328 0C DTCO acceleration to fight scaling stagnation (Invited Paper) [11328-11] 11328 0D Dynamic pattern matching flow to enable low escape rate weak point detection [11328-12] 11328 OE Integrating enhanced hotspot library into manufacturing OPC correction flow [11328-13] 11328 OF Exploring patterning limit and enhancement techniques to improve printability of 2D shapes at **3nm node** [11328-33]

	DFM BY CHIP MAKERS
11328 OH	Foundry approach for layout risk assessment through comprehensive pattern harvesting and large-scale data analysis [11328-15]
11328 01	Process related yield risk mitigation with in-design pattern replacement for system ICs manufactured at advanced technology nodes [11328-16]
	DESIGN FOR MANUFACTURING
11328 OL	Systematic DTCO flow for yield improvement at 14/12nm technology node [11328-19]
11328 OM	Co-optimizing DFM enhancements and their impact on layout-induced circuit performance for analog designs [11328-20]
11328 ON	Enabling nanoimprint simulator for quality verification; process-design co-optimization toward high volume manufacturing [11328-21]
11328 00	Process variation-aware mask optimization with iterative improvement by subgradient method and boundary flipping $[11328-22]$
	DEVICE AND INTEGRATION
-	
11328 0Q	Efficient design of guard rings and antenna diodes to improve manufacturability of FDSOI circuits [11328-24]
11328 OR	Cost-performance optimization of fine-pitch W2W bonding: functional system partitioning with heterogeneous FEOL/BEOL configurations [11328-25]
11328 0\$	How utilizing curvilinear design enables better manufacturing process window [11328-26]
	DPTCO FROM EQUIPMENT VENDORS
11328 0V	Holistic method for reducing overlay error at the 5nm node and beyond (Invited Paper) [11328-29]
	DPTCO FROM EDA VENDORS
11000 000	
11328 OW	New approaches to physical verification closure and cloud computing come to the rescue in the EUV era (Invited Paper) [11328-30]

Multi-varied implementations with common underpinnings in design technology cooptimization (Invited Paper) [11328-32]

POSTER SESSION

11328 OZ	An advanced and efficient methodology for process setup and monitoring by using process stability diagnosis in computational lithography [11328-34]
11328 10	Via optimization methodology for enhancing robustness of design at 14/12nm technology node [11328-35]
11328 12	Explore process weak patterns for manufacturing friendly design [11328-39]
11328 14	VIA design optimization for fast yield ramping in advanced nodes [11328-41]
11328 16	Early detection of Cu pooling with advanced CMP modeling [11328-43]
11328 17	CMP simulation-based dummy fill optimization [11328-44]
11328 18	An efficient way to accelerate litho hotspot checking [11328-45]
11328 19	Kissing corner handling in advanced nodes [11328-46]
11328 1A	DFM: "Design for Manufacturing" or "Design Friendly Manufacturing" How to convert extra EPE budget into design freedom by SMO [11328-47]
11328 1B	Fast OPC repair flow based on machine learning [11328-48]
11328 1C	A comprehensive standard cell library qualification to prevent lithographic challenges [11328-49]
11328 1D	Implementing Machine Learning for OPC retargeting [11328-50]
11328 1E	A feature selection method for weak classifier based hotspot detection [11328-51]
11328 1G	Unsupervised machine learning based CD-SEM image segregator for OPC and process window estimation [11328-53]

Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Abdelghany, Hesham, 05
Abdelrazek, Abdelrahman, 08
Abdulghany, Ahmed, 0M
Aihara, Sentaro, 0N
Alaa, Mostafa, 08
Asaka, Yukio, 06
Asano, Toshiya, 0N
Azuma, Rina, 0O
Baek, Seunghee, 06
Bahnasawi, Mohamed, 08
Bakshi, Janam, 0D, 0M
Batarseh, Fadi, 0D
Bayoumi, Magdy A., 1G
Beyne, Eric, 0R

Beyne, Eric, OR Braam, Kyle, 06 Cao, Yun, 17 Cerbu, Dorin, 1G

Chanemougame, Daniel, 0C

Chao, Hung-Wen, 1A Chee, Jansen, 16 Chehab, Bilal, 07, 0A Chen, Ao, 1A Chen, Lijun, 0Z Chen, Rui, 0L, 10 Chen, Ryan, 06 Chen, Sun, 1B

Chen, Zhixi, 14, 17, 18, 1C Cheng, Guojie, 0Z Cheng, Nai-Chia, 1D Chiu, Eric, 0H Choi, Soo-Han, 0Y Churchill, Peter, 0C Cobb, Jonathan, 0C Condella, Jac, 0l Das, Sayantan, 1G Debacker, Peter, 0R Deng, Rock, 1B Dey, Bappaditya, 1G Dong, Lisong, 0L, 10

Du, Chunshan, OL, 10, 12, 14, 17, 18, 1C

El-Manhawy, Wael, 03, 08, 12 Elsemary, Ahmed Mounir, 0D

Falch, Bradley J., 0E Fan, Xuedong, 0Z Ferguson, John, 0W Fu, Jiunhau, 0E Fujimura, Aki, 0S Gan, Quan, 1A Gao, Gen-Sheng, 1A Gbondo-Tugbawa, Tamba, 16

Ge, Yancong, 0Z
Gennari, Frank E., 0l
Ghulghazaryan, Ruben, 17
Gower-Hall, Aaron, 16
Guajardo, Marco, 05, 1D
Halder, Sandip, 1G
Hamed-Fatehy, Ahmed, 0F
Hammouda, Sherif, 08
Hanafusa, Ken, 06
Higuchi, Jiro, 06
Ho, Chia-Tung, 0C
Hooker, Kevin, 05, 1D
Hou, Frank, 12, 18
Hsu, Single, 16
Hu, Chan-Yuan, 1A

Hu, Xinyi, OL, 10, 12, 14, 17, 18, 1C

Huang, Elven, 12 Huang, Tengyen, 0E Huda, Gazi, 19 Huda, Rais, 0M Hurat, Philippe, 0I Ismail, Mohamed, 03 Jang, D., 07

Hu, Kuan, 12

Jeon, Joong-Won, Ol Jiang, Jet, 12, 18 Jiang, Liwei, 17 Kabeel, Aliaa, 03, 08 Kang, Jae-Hyun, Ol Katzman, Gail, 0M Khalil, Kasem, 1G Khater, Ahmed, 03 Kim, Jaehwan, Ol Kim, Jin Hee, 08 Kim, Jin, Ol Kim, John, 0Y Kim, Ryoung Han, 1G

Kiyohara, Naoki, 0N
Kodama, Chikaaki, 0O, 1E
Kohira, Yukihide, 0O
Kotb, Rehab, 0F
Kwan, Joe, 03, 08, 0L
Lai, Ya-Chieh, 0I, 16
Lee, Brian, 16
Lee, Sangah, 0I
Lee, SeungJo, 08
Lee, Zhao Chuan, 09, 0M
Leray, Philippe, 1G

Li, Gavin, 12, 18 Liao, Chuncheng, 0E Liao, Wenkui, 0Z Liebmann, Lars, 0C Lin, Eason, 16

Liu, Zhengfang, 12, 14, 17, 18, 1C

Lu, Chia-Chun, 05 Lucas, Kevin, 0Y Ma, Marfe, 12

Ma, Marre, 12
Madhavan, Sriram, 0H, 0M
Madkour, Kareem, 08
Malik, Shobhit, 0H
Mashita, Hiromitsu, 06
Matsui, Tomomi, 0O
Mehrotra, Vikas, 0M
Mendoza, Harold, 19
Milojevic, Dragomir, 0R

Mendoza, Harold, 19 Milojevic, Dragomir, 0R Moroz, Victor, 0C, 0Y Murali, Kiruthika, 0H Nagane, Kohei, 0N Nakayama, Takahiro, 0N Narioka, Shintaro, 0N

Niewczas, Mariusz, OS Nojima, Shigeki, O6 Oguchi, Yuichiro, ON Ogura, Hiroki, 1E Omran, Ahmed, O6

Ong, Jonathan Yoong Seang, 09

O'Riordan, Don, OS Pang, Leo, OS Park, Jongha, O8 Park, Joo Hyun, OH Pathak, Piyush, OI Pearman, Ryan, OS Piliposyan, Davit, 17 Poluju, Praneetha, OH Rabie, Asmaa, O3 Ramesh Babu, Monisa,

Ramesh Babu, Monisa, 0H Rezaeifakhr, Pouya, 0H Rizk, Sarah, 03, 08 Ryan, Deborah, 0H Ryckaert, Julien, 07, 0A

Sabry, Nabil, 08 Sato, Shimpei, 1E

Schroeder, Uwe Paul, 0D, 0M

Schioeder, twe radi, Seki, Junichi, ON Selvam, Punitha, 09 Shafee, Marwah, 08 Sherazi, Yasser, 1G Shi, Bailing, 1B Shin, Byungchul, Ol Shiode, Yoshihiro, ON Shu, Zhongli, 1B Simcoe, Michael, OM

Smith, Jeffrey, OC Socha, Robert, OV Song, Shenghua, OH

Spessot, Alessio, 07, 0A

Su, Xiaojing, OL, 10 Su, Yajuan, OL, 10 Suzuki, Koshiro, 0N Takahashi, Atsushi, 0O, 1E Takahashi, Hidekazu, 1E Takaki, Takamasa, 06

Tan, Elsley, OE
Taoka, Hironobu, O6
Tipple, Dave, OQ
Tripathi, Vikas, O9
Tsai, John, OE
Tseng, I-Lun, O9
Tsuei, Tim, OY

Tu, Yuanying, 1B Ungar, Jeff, 0S

Van der Plas, Geert, OR

Venkatachalam, Panneerselvam, 0H

Verkest, Diederik, 07, 0A Vikram, Abhishek, 0Z

Wan, Qijian, OL, 10, 12, 14, 17, 18, 1C

Wang, Ethan, 16 Wang, Hui, OZ Wang, Jane, OR Wang, Lynn, OM Wang, Min, 14 Wang, Weiting, 06 Wang, Xiaolong, OZ Weckx, Pieter, O7, OA

Wei, Fang, 17 Wei, Yayi, OL, 10 Wilson, Jeff, 17 Word, James, 0F Wu, Linghui, 0E

Xiao, Guangming, 06, 1D

Xie, Qian, 0H Xu, QiXin, 1 A Yin, Haizhou, 0H

Yip, Chun Ming Tommy, 09

Yu, Shirui, 14 Yuan, Chi-Min, 0Q Zhang, Jiao, 17 Zhang, Libin, 10 Zhang, Qing, 0Z Zhang, Recoo, 0L Zhang, Yizhong, 14 Zhang, Yu, 0Z, 1A Zheng, Haichang, 0Z Zhou, Wenzhan, 1A

Zhu, Jun, OZ Zhu, Yu, 1B

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